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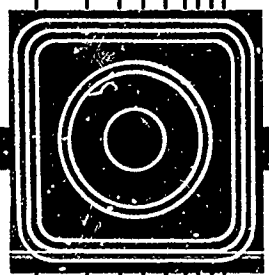
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SUBJECT INDEX:
MIL-HDBK-338
ELECTRONIC
RELIABILITY
DESIGN
HANDBOOK

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***SUBJECT INDEX
TO
MIL-HDBK-338
ELECTRONIC
RELIABILITY
DESIGN HANDBOOK
1989***

Prepared by:

Reliability Analysis Center
PO Box 4700
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Under contract to:

Rome Air Development Center
Griffiss AFB, NY 13441-5000

Reliability Analysis Center

A DoD Information Analysis Center

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REPORT DOCUMENTATION PAGE

Form Approved
OMB No. 0704-0188

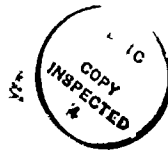
1a. REPORT SECURITY CLASSIFICATION Unclassified			1b. RESTRICTIVE MARKINGS		
2a. SECURITY CLASSIFICATION AUTHORITY			3. DISTRIBUTION/AVAILABILITY OF REPORT Approved for public release; distribution unlimited. Available from RAC or DTIC: Microfiche only available from DTIC.		
2b. DECLASSIFICATION/DOWNGRADING SCHEDULE			4. PERFORMING ORGANIZATION REPORT NUMBER(S) MIL-HDBK-338		
6a. NAME OF PERFORMING ORGANIZATION Reliability Analysis Center			6b. OFFICE SYMBOL (If applicable) DTIC/DF		7a. NAME OF MONITORING ORGANIZATION RADC/RBE
6c. ADDRESS (City, State, and ZIP Code) P.O. Box 4700 Rome, NY 13440-8200			7b. ADDRESS (City, State, and ZIP Code) Griffiss AFB, NY 13441-5700		
8a. NAME OF FUNDING/SPONSORING ORGANIZATION DLA/DTIC		8b. OFFICE SYMBOL (If applicable) DTIC/DF		9. PROCUREMENT INSTRUMENT IDENTIFICATION NUMBER F30602-87-C-0228	
8c. ADDRESS (City, State, and ZIP Code) DTIC Cameron Station Alexandria, VA 22314-6145			10. SOURCE OF FUNDING NUMBERS		
			PROGRAM ELEMENT NO. 65802S	PROJECT NO. 1.0	WORK UNIT ACCESSION NO.
11. TITLE (Include Security Classification) Index to MIL-HDBK-338					
12. PERSONAL AUTHOR(S)					
13a. TYPE OF REPORT		13b. TIME COVERED FROM _____ TO _____		14. DATE OF REPORT (Year, Month, Day)	
				15. PAGE COUNT	
16. SUPPLEMENTARY NOTATION Hard copies available from: Reliability Analysis Center, P.O. Box 4700, Rome, NY 13440-8200. (Price \$25.00). DTIC will provide microfiche copies at standard microfiche price.					
17. COSATI CODES			18. SUBJECT TERMS (Continue on reverse if necessary and identify by block number)		
FIELD	GROUP	SUB-GROUP	Index		
			Reliability Design		
19. ABSTRACT (Continue on reverse if necessary and identify by block number)					
MIL-HDBK-338, entitled "Electronic Reliability Design Handbook" is a very comprehensive handbook for use by design engineers, reliability engineers and managers to design, produce and deploy reliable and maintainable electronic systems. The handbook itself contains no subject index and can therefore be very awkward to use. The intent of this subject index is to provide a means by which specific topics and subjects can be located within the handbook. Next to each index term is the volume and page that the topic appears on. <i>Reliability electronic/handbooks;</i> <i>Electronic equipment/handbooks.</i> <i>(FDC) - f</i>					
20. DISTRIBUTION/AVAILABILITY OF ABSTRACT ☐ UNCLASSIFIED/UNLIMITED ☐ SAME AS RPT. ☐ DTIC USERS			21. ABSTRACT SECURITY CLASSIFICATION		
22a. NAME OF RESPONSIBLE INDIVIDUAL Steven J. Flint, RAC Technical Director			22b. TELEPHONE (Include Area Code) (315) 337-0900		22c. OFFICE SYMBOL

PREFACE

MIL-HDBK-338, "Electronic Reliability Design Handbook" is a comprehensive 1500 page handbook for use by design engineers, reliability engineers and managers to specify, design, produce, acquire and deploy reliable and maintainable electronic systems. The handbook itself contains no subject index and is therefore very awkward to use.

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Accession For	
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DTIC TAB	☐
Unannounced	☐
Justification	
By <i>HC #25.00</i>	
Distribution/	
Availability Codes	
Dist	Avail and/or Special
<i>A-1</i>	<i>24</i>



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